

ABSTRACT

A method of manufacturing an adhesive film for use in semiconductor device manufacture according to the present disclosure includes, in this order, (A) a step of preparing a laminate having at least a strip-shaped carrier film having a width of 100 mm or less and an adhesive layer formed to cover a surface of the carrier film, and (B) a step of die cutting the adhesive layer to obtain a plurality of adhesive pieces disposed on the carrier film to be arranged in a longitudinal direction of the carrier film, in which when the die cutting is performed in the step (B), a cut is formed with respect to the adhesive layer and the carrier film to satisfy the condition shown in the following Inequality (1), and the adhesive piece has a shape with at least one of a projection and a recess formed on at least one side of a rectangle or a square:

$$0 < D/T \leq 0.6 \quad (1)$$

in the inequality, D is a depth (unit: μm) of the cut with respect to the carrier film, and T is a thickness (unit: μm) of the carrier film.